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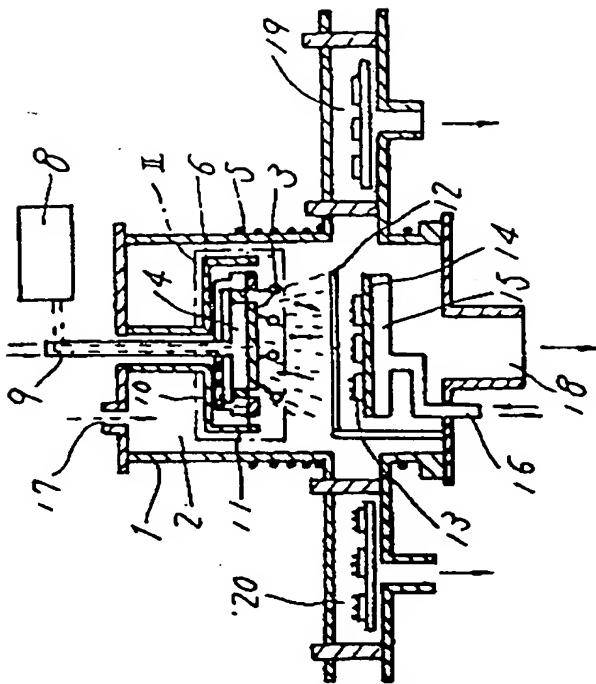
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TITLE : METHOD AND DEVICE FOR FORMING
 FILM



ABSTRACT : PURPOSE: To stick a coating material on the resulting product of sputtering sticking on the inside surface of a sputtering device and to prevent the resulting product of sputtering from falling onto a material to be treated by providing a target for coating separately from a target for film formation into the sputtering device and changing over alternately a power source for the same.

CONSTITUTION: A holder 14 on which a wafer 13 to be treated is placed is put into a vacuum vessel 1 of a sputtering vessel, and a target 3 for film formation with sputtering and a target 5 for coating film consisting of Al are disposed above the holder. A DC voltage is impressed between the target 3 and the grounded holder 14 from an electric power source and gaseous Ar is introduced through an inlet 17 to generate glow discharge, thereby forming the film of the target material on the surface of the wafer 13. The resulting product of sputtering sticks in the vacuum vessel as well as Al is coated on the resulting product of sputtering by changing over the voltage on the Al target 5 in order to prevent said product from falling onto the wafer and deteriorating the quality of the wafer. The falling of said product onto the wafer is thus prevented.

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